

BOSON®

High-Performance LWIR Thermal Camera Modules

www.flir.com/**boson**

SEE FARTHER, FASTER & MORE CLEARLY

ABOUT TELEDYNE FLIR



With nearly **sixty models**, the NDAA compliant and ITAR-free Boson family represents the most **dynamic**, **highest-performing** uncooled thermal imaging technology in the Teledyne FLIR portfolio. The **small**, **lightweight**, **and low-power** OEM package features multiple configurations and onboard image processing for qualitative and quantitative thermal imaging applications.

See what solution is best for you.

Teledyne FLIR designs, develops, manufactures, markets, and distributes technologies that enhance perception and awareness. We bring innovative sensing solutions into daily life through our thermal imaging, visible-light imaging, video analytics, measurement and diagnostic, and advanced threat detection systems.

Teledyne FLIR offers a diversified portfolio that serves a number of applications in government & defense, industrial, and commercial markets. Our products help first responders and military personnel protect and save lives, promote efficiency within the trades, and innovate consumerfacing technologies. Teledyne FLIR strives to strengthen public safety and well-being, increase energy and time efficiency, and contribute to healthy and intelligent communities.



MEET THE **BOSON FAMILY**

BOSON+

High Performance, **Uncooled**, LWIR **Thermal Camera** Module

NDAA compliant and ITAR free, the Boson+ sets the standard for longwave infrared (LWIR) OEM thermal camera performance and size, weight, and power (SWaP). It features an industry-leading thermal sensitivity of less than or equal to (<)20 mK and an upgraded automatic gain control (AGC) filter delivering dramatically enhanced scene contrast and sharpness. **Lower video latency** enhances tracking, seeker performance, and decision support. Radiometry will be available in the third guarter of 2024 on 640 x 512 and 320 x 256 resolution models.

Boson+ maintains the widely-deployed Boson mechanical, electrical, and optical interfaces enabling a **plug-and-play upgrade**. With customer-selectable USB, CMOS, or MIPI video interfaces, it is easier than ever to integrate Boson+ into a wider range of embedded processors from Qualcomm, Ambarella, and more. The userfriendly Boson SDK, GUI, and comprehensive product integration documentation further simplify OEM integration. Enhanced thermal performance and industry-leading reliability provide lowrisk development, making Boson+ ideal for unmanned ground vehicles (UGV), unmanned aircraft systems (UAS), wearables, security applications, handhelds, and thermal sights.

BOSON

Uncooled, LWIR **Thermal Camera** Module

NDAA compliant and ITAR free, the Boson sets the standard for SWaP. Utilizing Teledyne FLIR's advanced image processing and several industry-standard communication interfaces, Boson enables applications from firefighting to unmanned aircraft systems (UAS), security, and automotive development kits, all for as little as 600 mW.

The 12 µm uncooled detector comes in two resolutions - 640 x 512 or 320 x 256 – and multiple frame rate options. Radiometric models offer absolute temperature measurement. With multiple lens configurations, the easy-to-use Boson SDK, user-friendly GUI, and comprehensive integration documentation to further simplify integration into higher-level systems.

	BO	SON+		BOSON	
Resolution	VGA - 640 × 512 VOx Microbolometer QVGA - 336 × 256 VOx Microbolometer				
Pixel Pitch	12 µm				
Spectral Band		Longwave infra	ared; 8 µm – 14 µm		
Sensitivity (NEdT)	Industrial: <20 mK Professional: <30 mK		Industrial: <40 mK, Professional: <50 mK Consumer: <60 mK		
Frame Rate	60 Hz baseline; 30 Hz runtime selectable				
Non-uniformity Correction (NUC)	Factory calibrated; updated FFCs with FLIR Silent Shutterless NUC (SSN™)				
Solar Protection	Yes, lens only		Integral		
Digital Zoom	1x to 8x zoom				
f number	1.0				
Symbol Overlay	Re-w	ritable each frame; alph	a blending for translı	ucent overlay	
ADIOMETRY					
Temperature Measurement	Available on select models in the first quarter of 2025.		Yes, select models		
Scene Dynamic Range	320 × 256	640 × 512	320 × 256	640 × 512	
	to 150 °C (high gain) to 350 °C (low gain)	up to 140 °C (high gain)	to 140 °C (high ga	ain) to 500 °C (low gain	
Temperature Accuracy	±5 °C	C accuracy or less, depe	nding upon operatin	g conditions	
ENS OPTIONS					
Resolution	320 × 256	640 × 512	320 × 256	640 × 512	
Horizontal Field of View (HFOV);	92°; 2.3 mm	95°; 4.9 mm	92°; 2.3 mm	95°; 4.9 mm	
Effective Focal Length	50°; 4.5 mm	50°; 9.2 mm	50°; 4.3 mm	50°; 8.7 mm	
	50°; 4.3 mm	32°; 14 mm	34°; 6.3 mm	50°; 9.2 mm	
	34°; 6.3 mm	24°; 18 mm	24°; 9.1 mm	32°; 13.6 mm	
	24°; 9.1 mm	18°; 24 mm	16°; 14 mm	32°; 14 mm	
	16°; 13.8 mm	12°; 36 mm	12°; 18 mm	24°; 18 mm	
	12°; 18 mm	8°; 55 mm	6°; 36 mm	18°; 24 mm	
	6°; 36 mm	6°; 73 mm	4°; 55 mm	12°; 36 mm	
	4°; 55 mm			8°; 55 mm	
	Available without lens			6°; 73 mm	
HYSICAL ATTRIBUTES					
Size		21 × 21 × 11 mm (0.83 >	$(0.83 \times 0.43 \text{ in})$ with	out lens	
Weight			oz) without lens		
Precision Mounting Holes	1000 million		16x0.35 (rear cover)		
Input Voltage		7	3 VDC		
Power Consumption	3. 320+ as low as 500 mW 640+ as low as 1000 mW		Varies	by configuration; ow as 600 mW	
Video Channels	CMOS, MIPI or USB3		CMOS or USB2		
Peripheral Channels		I2C, SPI, SDIO			
Control Channels	UART, USB or I2C		UART or USB		
Configurable GPIO			ser configurable		
NVIRONMENTAL					
Operating Temperature Range		-40 °C to 80 °	C (-40 °E to 176 °E)		
Non-Operating Temperature Range	-40 °C to 80 °C (-40 °F to 176 °F) -50 °C to 85 °C (-58 °F to 185 °F)				
Shock	1,500 g @ 0.4 msec				
Operational Altitude	1.2 1/100	(max altitude of a comm		orno platform)	

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3.3 VDC		
320+ as low as 500 mW 640+ as low as 1000 mW	Varies by configuration; as low as 600 mW	
CMOS, MIPI or USB3	CMOS or USB2	
I2C, SPI, SDIO		
UART, USB or I2C	UART or USB	
Up to 11; user configurable		
-40 °C to 80 °C (-40 °F to 176 °F)		
-50 °C to 85 °C (-58 °F to 185 °F)		
1,500 g @ 0.4 msec		
12 km (max altitude of a commercial airliner or airborne platform)		
	320+ as low as 500 mW 640+ as low as 1000 mW CMOS, MIPI or USB3 I2C, SP UART, USB or I2C Up to 11; user -40 °C to 80 °C f -50 °C to 85 °C (1,500 g @	

ZOOM IN WITH **BOSON+CZ**

BOSON+CZ

High Performance, Uncooled, LWIR **Thermal Camera** Module with 5x **Continuous Zoom**

The ITAR-free Boson+ CZ 14-75 combines the Boson+ thermal camera module and 5x continuous zoom (CZ) lens offering a highperformance imaging solution. With **≤20 mK thermal sensitivity** and an upgraded automatic gain control (AGC) filter Boson+ CZ delivers dramatically enhanced scene contrast and sharpness. The high-performance lens and control electronics maintain focus through zoom and provide real-time thermal gradient compensation as well as flexibility for user-defined command syntax and expansion for additional features.

The Boson+ camera module and **14 to 75 mm** CZ lens are designed for each other, providing optimal performance and a single system warranty only achievable from a single source. The factory-integrated system lowers development and manufacturing risk and improves time-to-market, making the reliable Boson+ CZ 14-75 ideal for unmanned aerial vehicles, perimeter surveillance, light armored vehicle situational awareness and targeting, and soldier sighting systems.



BOSON+ CZ 14-75	_			
		ENVIRONMENTAL		
Resolution Pixel Pitch	640 × 512 12 μm	Operational Temperature Range	-40 °C to 80 °C (-40 °F to 176 °F)	
Spectral Band	Longwave infrared; 8 µm – 14 µm	Non Operating Temperature Range	-40 °C to 80 °C (-40 °F to 176 °F)	
Sensitivity (NEdT)	≤20 mK	Focus Over Temperature	Maintain focus from -35 °C to 70 °C (-31 °F to 158 °F)	
Frame Rate	60 Hz baseline; 30 Hz runtime selectable	IP Rating [at front of lens]	IP67	
Non-uniformity Correction (NUC)	Factory calibrated; updated FFCs with FLIR Silent Shutterless NUC (SSN™)	Protection and Anti-Reflection Coatings	Lens elements shall be coated with anti-reflection coatings subject to adhesion,moderate abrasion,	
Solar Protection	Yes, lens only		and humidity per	
Digital Zoom	1x to 8x zoom		durability requirements of MIL-PRF-13830	
Symbol Overlay	Re-writable each frame; alpha blending for translucent overlay	DLC Option	With DLC front coating, lens to withstand humidity, severe abrasion, and salt fog	
IMAGING & OPTICAL			exposure	
f number	1.2	ESS Thermal	Lens assembly to be subjected to -35 °C to +70 °C	
Focal Length	NFOV = 75mm +4% / -0% WFOV = 14mm +0% / -4%		temperature extremes with a maximum of 5 °C/min ramp	
Lens Window Transmittance	HEAR L1: >/= 84% for band 8-12 mm DLC L1: >/= 78% for band	ESS Vibration	rate and a minimum dwell of 60 min at each temperature extreme	
NFOV/WFOV Co-boresight location	8-12 mm <0.15 mm		Random vibration, from 10 Hz to 500 Hz with the following vibration profile along the optical axis for a minimum of	
Boresight Drift Through Zoom	<0.10 mm		10 minutes:	
Boresight Repeatability	= 0.025 mm</td <th></th> <td colspan="2" rowspan="2">at 10 Hz, 0.01 G2/Hz at 50 Hz, 0.01 G2/Hz at 80 Hz, 0.04 G2/Hz at 350 Hz, 0.04 G2/Hz at 500 Hz, 0.01 G2/Hz</td>		at 10 Hz, 0.01 G2/Hz at 50 Hz, 0.01 G2/Hz at 80 Hz, 0.04 G2/Hz at 350 Hz, 0.04 G2/Hz at 500 Hz, 0.01 G2/Hz	
Parfocality	At 20 °C the lens shall stay in focus through zoom within 1/4-wave at 10.6µm			
Minimum Focus Distance	NFOV > 18 m WFOV > 3 m	Shock	9G with 11msec half-sine pulse, minimum 3 pulses for each of 3 axes	
Distortion	WFOV <6%; NFOV < 1%	Design and Construction	Lens assembly to meet MIL- STD-1472 and MIL-HDBK-1686	
Relative Illumination	RI falloff < 10%; Flux change through zoom <4%	Operational Altitude	12 km (max altitude of a commercial airliner or airborne platform)	
Time to Zoom	<1.5 sec		pationity	
Time to Focus	<0.5 sec			
PHYSICAL ATTRIBUTES				
Size	101 (l) x 77 (w) x 77 (h) mm (3.97 x 3.03 x 3.03 in)			
Weight	390 g (13.75 oz)			
INTERFACING				

Power Supply	Nominal voltage 12V +/- 1V
Serial Communication	The following serial communications shall be set: RS232, 38400 baud, 1 stop bit, 8 data bits, no parity
Peripheral Channels	I2C, SPI, SDIO
Video Channels	CMOS, MIPI or USB3
Control Channels	UART, USB or I2C

THERMAL INTEGRATION MADE EASY

Integrating thermal camera modules is now easier with our library of how-to-videos, application notes, and our comprehensive support center with product drawings, datasheets, and more!





The simple optical interface accommodates integratordesigned optics and the industry's widest variety of lens options available.



INTERFACES

Commercial interfaces including MIPI (Boson+ only), USB and, CMOS, are all available with the Boson family.

SUPPORT

When developers need assistance, our highly qualified Technical Services team are available to support integration wherever you need it.

Please visit www.flir.com/TIME to access integration support material.



SIMPLIFY & STREAMLINE DEVELOPMENT

The Boson GUI provides developers key command capabilities that simplify and streamline development and testing with the Boson thermal camera modules. Integrators with the original Boson models require GUI 3.X & older, while Boson+ models require GUI 4.0 & newer.

- \bigcirc Operates on Windows 10 64-Bit or newer
- \bigcirc Isotherms with colorization bar and highly-configurable settings
- \bigcirc Spot meter with statistics and temperature bar
- External sync with additional sensors to enable data fusion
- Radiometry settings including t-linear, environmental parameters, emissivity, and more.





BOSON ACCESSORIES



Boson VPC (PN: 500-0869-00)

The USB Video Power Connector (VPC) kit turns the Neutrino LC camera into a webcam. Power, digital video, and comm are all via USB2. The kit includes a USB-A to USB-C cable.



Boson USB/Analog VPC Kit (PN: 421-0062-00)

The Boson video/power/control (VPC) is an accessory that adapts the native high-density electrical connector to a simpler USB-C interface. The Kit includes a VPC adapter, as well as a biurcated cable with USB-A (power/control) and BNC (video) connectors.



Boson VPC Cable (PN: 308-0271-00)

Biurcated cable with USB-A (power/control) and BNC (video) connectors.



Boson Camera Link Accessory Kit (PN: 421-0063-00)

Expansion board for Boson cameras that matches the functionality of the VPC module, and enables the camera to be interfaced to a Camera Link frame grabber, allowing the capture of digital 16-bit video data. (Does not include Camera Link cable, frame grab board, or data capture software.)

Boson Development Board (PN: 250-0705-00)

A breakout board is available for Boson users and integrators that need easy access to the Boson I/O and interfaces. This board is designed for development purposes, and is not intended or rated for long-term reliability over temperature. Improvements from the original breakout board (SKU 250-0593-00) include exposing the data_valid signal for CMOS video, selection for the power input while using USB (USB or externally supplied power through banana plug), and external sync input/output.



Boson VPC w/Cables (PN: 421-0061-00)

single or dual lane configurations

Provides all output options on a single PCB and easy access to the full 80-pin camera interface for development. Includes a flex cable between the board and the camera and a wire harness to the cooler interface.



tripod mounting.

Boson Lens Focus Tool (PN: 261-2609-00) A Boson lens focus tool is an accessory needed to change the focus of wide field of view lenses.



Boson MIPI Development Accessory Board (PN: 250-0853-00) The Boson MIPI development board supports a digital data protocol compatible with MIPI CSI v1.1 and DPHY 1.0 cameras, offering software-configurable

option available in the Tau camera models.

Boson Tripod Mount Adapter (PN: 261-2608-00) Black-anodized aluminum accessory that provisions for standard 1/4" x 20

12V 4" Blackbody for Gain Cal & Supplemental FFC (PN: 285-0029-02)

Teledyne FLIR offers 4-inch blackbody sources for customers that need a low-cost, uniform temperature source when using FLIR's Alt Lens Cal software to field-calibrate lens-less Photon or Tau cameras with third-party lenses, or to take advantage of the Supplemental Flat Field Correction (FFC)

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NOTES



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